- DUAL J.K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR DECEMBER 1983 - REVISED MARCH 1988
- · Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic
- Dependable Texas Instruments Quality and Reliability

#### description

These devices contain two independent J-K positiveedge-triggered flip-flops. A low level at the preset or clear inputs sets or resets the outputs regardless of the levels of the other inputs. When preset and clear are inactive (high), data at the J and K inputs meeting the setup time requirements are transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold time interval, data at the J and K inputs may be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by grounding K and tying J high. They also can perform as D-type flip-flops if J and K are tied together.

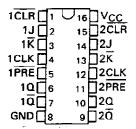
The SN54109 and SN54LS109A are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74109 and SN74LS109A are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each flip-flop)

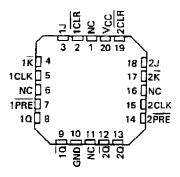
		PUTS			OUT	PUTS
PRE	CLR	CLK	J	K	a	ā
L	Н	×	х	Х	H	L
H	L	×	X	X	L	Н
L	L	X	Х	Х	Нţ	Нţ
Н	н	f	L	L	L	Н
н	H	t	Н	L	TOGG	GLE
н	Н	Ť	Ł	н	0.0	$\overline{\alpha}_0$
н	н	t	Н	н	Н	L
н	н	L	X	X		$\overline{a}_0$

<sup>†</sup> The output levels in this configuration are not guaranteed to meet the minimum levels for VOH if the lows at preset and clear are near VIL maximum. Furthermore, this configuration is nonstable; that is, it will not persist when preset or clear return to their inactive (high) level.

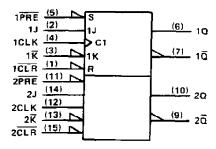
SN54109, SN54LS109A . . . J OR W PACKAGE SN74109 . . . N PACKAGE SN74LS109A . . . D OR N PACKAGE (TOP VIEW)



#### SN54LS109A . . . FK PACKAGE (TOP VIEW)



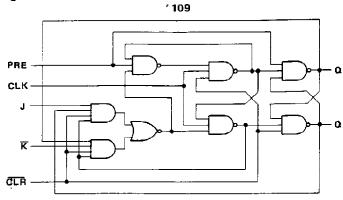
#### logic symbol‡



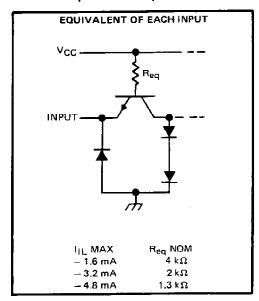
<sup>‡</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

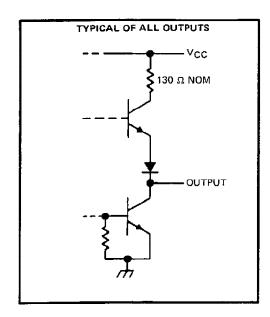
# logic diagram (positive logic)

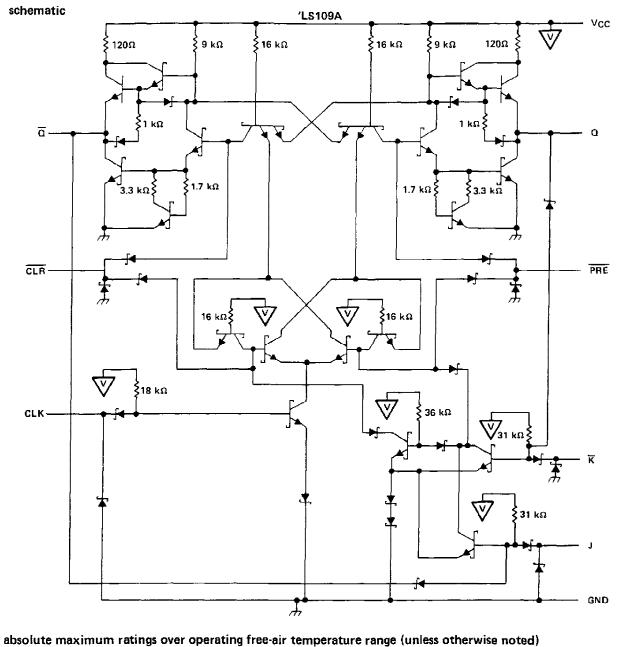


# schematics of inputs and outputs



109





Supply voltage, VCC (see Note 1)		7 V
Input voltage: '109	4 * * * * * * * * * * * * * * * * * * *	5.5 V
'LS109A		7 V
Operating free-air temperature range:	SN54'	- 55°C to 125°C
	SN74'	0°C to 70°C
Storage temperature range		- 65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



# SN54109, SN74109 DUAL J-K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

#### recommended operating conditions

				SN5410	)9		SN7410	9	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2			2			V
۷ıL	Low-level input voltage				8.0			0.8	V
ІОН	High-level output current				- 0.8			- 0.8	mΑ
IOL	Low-level output current				16			16	mA
	Pulse duration	CLK high or low	20			20			
tw.	ruise dui ation	PRE or CLR law	20			20			nş
tsu	Input setup time before CLK 1		10			10			ns
th	Input hold time-data after CLK1		6			6			ns
TΑ	Operating free-air temperature		~ 55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAR.	AMETER		TEST CONDITI	onet		SN5410	9		SN7410		UNIT
1211	AIVIETEIS !		1201 0010111		MIN	TYP‡	MAX	MIN	TYP‡	MAX	DIVIT
VIK		V <sub>CC</sub> = MIN,	= - 12 mA				<b>- 1.5</b>			- 1.5	V
VQН		V <sub>CC</sub> = MIN, I <sub>OH</sub> = - 0.8 mA	V <sub>IH</sub> = 2 V,	V <sub>IL</sub> ≈ 0.8 V,	2.4	3,4		2.4	3.4		V
VOL		V <sub>CC</sub> = MIN, I <sub>OL</sub> = 16 mA	V <sub>IH</sub> = 2 V,	V <sub>IL</sub> = 0.8 V,		0.2	0.4		0.2	0.4	v
11		V <sub>CC</sub> = MAX,	V <sub>I</sub> = 5.5 V	<u> </u>			1			1	mA
	J or K						40			40	
1	CLR	V <sub>CC</sub> = MAX,	V. ~ 2.4.V				160			160	
НII	PRE or CLK	*CC 1417177					80			80	μА
	Jor K €		<u> </u>				- 1.6			- 1.6	
1	CLR <sup>1</sup>	V <sub>CC</sub> = MAX,	V. = 0.4 V				- 4.8			- 4.8	mΑ
IIE.	PRE¶	OCC - MAX,	V = 0.4 V				- 3.2			- 3.2	
	CLK		- ·		-		- 3.2			-3.2	
los §		V <sub>CC</sub> = MAX			- 30		- 85	- 30	* ***	- 85	mA
ICC#		VCC = MAX,	See Note 2			9	15		9	15	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: With all outputs open. ICC is measured with the Q and Q outputs high in turn. At the time of measurement, the clock input is grounded,

# switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST COND	ITIONS	MIN	TYP	MAX	UNIT
f <sub>max</sub>					25	33		MHz
<sup>t</sup> PLH	PRE	O.				10	15	ns
₹₽HL		ā				23	35	ns
<sup>t</sup> PLH	CLR	ব	$R_L = 400 \Omega$ ,	CL = 15 pF		10	15	ns
tpHL		a				17	25	ns
TPLH	CLK	QorQ				10	16	ns
<sup>t</sup> PHL		1 20, 2				18	28	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



<sup>&</sup>lt;sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25 \,^{\circ}\text{C}$ .

<sup>&</sup>lt;sup>5</sup> Not more than one output should be shorted at a time.

<sup>1</sup> Clear is tested with preset high and preset is tested with clear high.

<sup>#</sup> Average per flip-flop.

# SN54LS109A, SN74LS109A DUAL J-K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

## recommended operating conditions

			s	N54LS1	09A	SI	11811		
			MIN	MOM	MAX	MIN	NOM	MAX	UNIT
v <sub>CC</sub>	Supply voltage		4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voitage		2			2			V
VIL	Low-level input voltage				0.7			0.8	V
Гон	High-level output current		T		- 0.4		••	- 0.4	mA
ТОЦ	Low-level output current				4			8	mA
fclock	Clock frequency		0		25	0		25	MHz
	Pulse duration	CLK high	25		_	25	_		
t <sub>w</sub>	ruise duration	PRE or CLR low	25			25			ns
	Service before CL K 4	High-level data	35			35			
t <sub>\$u</sub>	Setup time before CLK 1	Low-level data	25			25			ns
th .	Hold time-data after CLK↑		5			5			ns
TA	Operating free-air temperature		- 55		125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITION	SN	154LS10	9A	SN				
FARAINE I ER		TEST COMPLITION	19.	MIN	TYP#	MAX	MIN	TYP‡	MAX	דומט
Vik	VCC - MIN,	I <sub>I</sub> = - 18 mA	•			<b>– 1.5</b>			_ 1.5	V
VOH	V <sub>CC</sub> = MIN, I <sub>OH</sub> = - 0.4 mA	V <sub>IH</sub> = 2 V,	V <sub>IL</sub> = MAX,	2.5	3.4		2.7	3.4		V
	V <sub>CC</sub> = MIN, I <sub>OL</sub> = 4 mA	VIL = MAX,	V <sub>IH</sub> = 2 V,		0.25	0,4		0.25	0.4	V
VOL	V <sub>CC</sub> = MIN, I <sub>OL</sub> = 8 mA	VIL = MAX,	V <sub>1H</sub> = 2 V,					0.35	0.5	\ \ \
J, K or CLK	Vcc = MAX,	V <sub>1</sub> = 7 V				0.1			0.1	mΑ
CLR or PRE	VCC - MAX,	. 41-14				0.2			0.2	ПІА
J, R or CLK	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.7 V				20			20	
TH CLR or PRE	1 vCC - WAA,	V   - 2.7 V				40		-	40	μΑ
J, K or CLK	VCC = MAX,	V <sub>I</sub> = 0.4 V				- 0.4			- 0.4	
CLR or PRE	ACC - MAY	V   - 0,4 V				- 0.8			- 0.8	mA
OS§	V <sub>CC</sub> = MAX,	See Note 4	_	- 20		<del></del> 100	- 20		- 100	mA
ICC (Total)	V <sub>CC</sub> = MAX,	See Note 2			4	8		4	8	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions,

NOTE 2: With all outputs open, ICC is measured with the Q and Q outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with V<sub>O</sub> = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively with the minimum and maximum limits reduced to one half of their stated values.

# switching characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f <sub>max</sub>				25	33		MHz
<sup>t</sup> PLH	CLR, PRE	Q or Q	$R_{\perp} = 2 k\Omega$ , $C_{\perp} = 15 pF$		13	25	ns
tPHL_	or CLK				25	40	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



<sup>‡</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C. §Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.





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# **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/30109B2A	NRND	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30109B2A	
JM38510/30109BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109BEA	Samples
JM38510/30109BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109BEA	Samples
JM38510/30109BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109BFA	Samples
JM38510/30109BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109BFA	Samples
JM38510/30109SEA	NRND	CDIP	J	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109SEA	
JM38510/30109SEA	NRND	CDIP	J	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109SEA	
JM38510/30109SFA	NRND	CFP	W	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109SFA	
JM38510/30109SFA	NRND	CFP	W	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109SFA	
M38510/30109B2A	NRND	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30109B2A	
M38510/30109B2A	NRND	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30109B2A	
M38510/30109BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109BEA	Samples
M38510/30109BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109BEA	Samples
M38510/30109BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109BFA	Samples
M38510/30109BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109BFA	Samples
M38510/30109SEA	NRND	CDIP	J	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109SEA	
M38510/30109SEA	NRND	CDIP	J	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109SEA	





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Orderable Device	Status	Package Type		Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
M38510/30109SFA	NRND	CFP	W	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109SFA	
M38510/30109SFA	NRND	CFP	W	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30109SFA	
SN54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS109AJ	Samples
SN54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS109AJ	Samples
SN74109N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74109N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS109AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS109A	Samples
SN74LS109AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS109A	Samples
SN74LS109ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS109A	Samples
SN74LS109ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS109A	Samples
SN74LS109ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS109A	Samples
SN74LS109ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS109A	Samples
SN74LS109AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS109AN	Samples
SN74LS109AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS109AN	Samples
SN74LS109AN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS109AN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS109ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS109AN	Samples
SN74LS109ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS109AN	Samples
SN74LS109ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS109A	Samples
SN74LS109ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS109A	Samples



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# PACKAGE OPTION ADDENDUM

28-Nov-2015

Orderable Device	Status	Package Type	•	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SNJ54LS109AFK	NRND	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 109AFK	
SNJ54LS109AFK	NRND	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 109AFK	
SNJ54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS109AJ	Samples
SNJ54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS109AJ	Samples
SNJ54LS109AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS109AW	Samples
SNJ54LS109AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS109AW	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



# **PACKAGE OPTION ADDENDUM**

28-Nov-2015

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#### OTHER QUALIFIED VERSIONS OF SN54LS109A, SN54LS109A-SP, SN74LS109A:

Catalog: SN74LS109A, SN54LS109A

Military: SN54LS109A

• Space: SN54LS109A-SP

NOTE: Qualified Version Definitions:

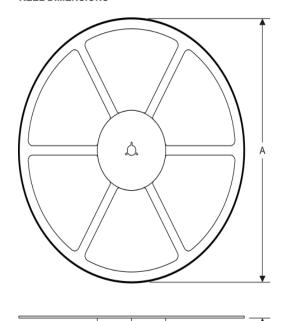
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

# PACKAGE MATERIALS INFORMATION

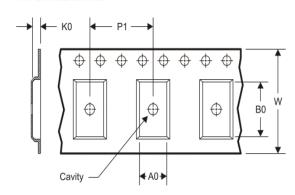
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# TAPE AND REEL INFORMATION

### REEL DIMENSIONS



### TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

# TAPE AND REEL INFORMATION

### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS109ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS109ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS109ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS109ANSR	SO	NS	16	2000	367.0	367.0	38.0

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